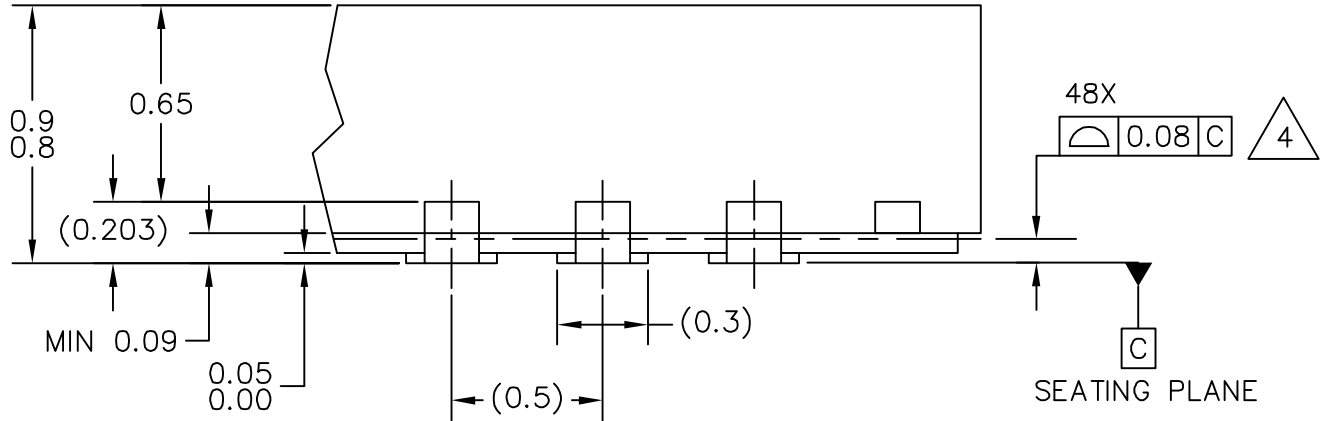


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TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.85, 0.5 PITCH, 48 TERMINAL	DOCUMENT NO: 98ASA00897D      REV: A	
	STANDARD: NON-JEDEC	
	SOT619-24	05 AUG 2016




DETAIL G  
VIEW ROTATED 90°CW

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	STANDARD: NON-JEDEC	
	SOT619-24	05 AUG 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH PAD.
5. MIN METAL GAP SHOULD BE 0.2 MM.

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